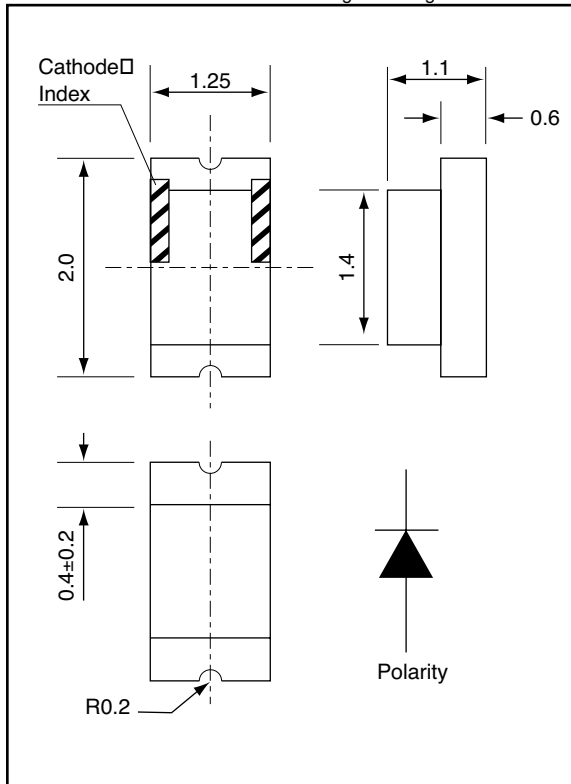




Weight: 2.0 mg Unit: mm



AND40A

InGaAlP Ultra Bright Orange Light Emission

Surface Mount Package

Features

- Small package size
- 2.0 (l) x 1.25 (w) x 1.1 (h) size
- Suitable for DIP and REFLOW soldering
- Recommended Forward Current: 10 mA

• RoHS Compliant

Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Rating	Unit
Forward Current	I_F	25	mA
Reverse Voltage	V_R	4	V
Power Dissipation	P_D	62.5	mW
Operating Temperature Range	T_{Opr}	-30 to 85	$^\circ\text{C}$
Storage Temperature Range	T_{Stg}	-30 to 85	$^\circ\text{C}$

Electro-Optical Characteristics ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V_F	$I_F = 20 \text{ mA}$	-	2.0	2.8	V
Reverse Current	I_R	$V_R = 4 \text{ V}$	-	-	100	μA
Luminous Intensity	I_V	$I_F = 20 \text{ mA}$	27	60	-	mcd
Peak Emission Wavelength	I_P	$I_F = 20 \text{ mA}$	-	612	-	nm
Spectral Line Half Width	$\Delta\lambda$	$I_F = 20 \text{ mA}$	-	15	-	nm
Dominant Wavelength	λ_d	$I_F = 20 \text{ mA}$	-	605	-	nm
Full Viewing Angle	θ	$I_V = 1/2 \text{ Peak}$	-	140	-	degree

Precaution

Please be careful of the following:

1. Manual soldering: maximum temperature of iron tip: 260°C max.
Soldering time: within 5 sec. per solder-land
Soldering portion of lead: up to 1.6 mm from the body of the device
2. Reflow solder: recommended condition is as follows:

Product specifications contained herein may be changed without prior notice. It is therefore advisable to contact Purdy Electronics before proceeding with the design of equipment incorporating this product.

